

IN THE CLAIMS

A listing of all claims and their current status in accordance with 37 C.F.R. § 1.121(c) is provided below.

1. (Currently Amended) A temporary holding surface having a plurality of semiconductor die stacks thereon, the temporary holding surface configured to temporarily hold the plurality of semiconductor die stacks, wherein each of the plurality of semiconductor die stacks comprises at least two semiconductor die permanently coupled together by adhesive, wherein the stack of at least two semiconductor die comprises a known good die stack, and wherein the plurality of semiconductor die stacks do not include ~~a lead frame or~~ a substrate.
2. (Previously Presented) The temporary holding surface, as set forth in claim 1, comprising a tape reel having the plurality of semiconductor die stacks thereon.
3. (Withdrawn – Previously Presented) The temporary holding surface, as set forth in claim 1, comprising a gel pack having the plurality of semiconductor die stacks thereon.
4. (Withdrawn – Previously Presented) The temporary holding surface, as set forth in claim 1, comprising a tray having the plurality of semiconductor die stacks thereon.
5. (Previously Presented) The temporary holding surface, as set forth in claim 1, wherein each of the plurality of semiconductor die stacks comprises at least three semiconductor die, each of the semiconductor die being permanently coupled together by the adhesive, wherein the adhesive has been set by curing.
6. (Previously Presented) The temporary holding surface, as set forth in claim 1, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

7. (Previously Presented) The temporary holding surface, as set forth in claim 1, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.
8. (Canceled)
9. (Previously Presented) The temporary holding surface, as set forth in claim 1, wherein at least one of the at least two semiconductor die comprises a memory die.
10. (Currently Amended) A tape reel having a plurality of semiconductor die stacks thereon, the tape reel configured to temporarily hold the plurality of semiconductor die stacks, wherein each of the plurality of semiconductor die stacks comprises at least two semiconductor die coupled together by set adhesive that has been cured, wherein each of the plurality of semiconductor die stacks comprises a known good die stack, and wherein the plurality of semiconductor die stacks do not include ~~a lead frame or~~ a substrate.
11. (Previously Presented) The tape reel, as set forth in claim 10, wherein each of the plurality of semiconductor die stacks comprises at least three semiconductor die, each of the semiconductor die being coupled together by the set adhesive.
12. (Previously Presented) The tape reel, as set forth in claim 10, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.
13. (Previously Presented) The tape reel, as set forth in claim 10, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.
14. (Canceled)

15. (Previously Presented) The tape reel, as set forth in claim 10, wherein at least one of the at least two semiconductor die comprises a memory die.

16. (Withdrawn – Currently Amended) A gel pack having a plurality of semiconductor die stacks thereon, the gel pack being adapted to temporarily hold the plurality of semiconductor die stacks, wherein each of the plurality of die stacks has been cured such that at least two semiconductor die in each of the plurality of die stacks are coupled together via a set adhesive, wherein each of the die stacks comprise a known good die stack.

17. (Canceled)

18. (Withdrawn) The gel pack, as set forth in claim 16, wherein one of the at least two semiconductor die is thicker than a second of the at least two semiconductor die.

19. (Withdrawn) The gel pack, as set forth in claim 16, wherein the topside surface area of one of the at least two semiconductor die is less than the topside surface area of a second of the at least two semiconductor die.

20. (Withdrawn – Previously Presented) The gel pack, as set forth in claim 16, wherein the at least two semiconductor die are configured as a shingle stack.

21. (Withdrawn) The gel pack, as set forth in claim 16, wherein at least one of the at least two semiconductor die comprises a memory die.